



US 20240237489A9

(19) **United States**  
(12) **Patent Application Publication**  
**KIM et al.**

(10) **Pub. No.: US 2024/0237489 A9**  
(48) **Pub. Date: Jul. 11, 2024**  
**CORRECTED PUBLICATION**

(54) **ELECTRONIC DEVICE AND METHOD FOR MANUFACTURING THE SAME**

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(21) Appl. No.: **18/355,197**

(22) Filed: **Jul. 19, 2023**

**Prior Publication Data**

(15) Correction of US 2024/0138236 A1 Apr. 25, 2024  
See (22) Filed.  
See (30) Foreign Application Priority Data.

(65) US 2024/0138236 A1 Apr. 25, 2024

**Foreign Application Priority Data**

Oct. 20, 2022 (KR) ..... 10-2022-0135955

**Publication Classification**

(51) **Int. Cl.**  
**H10K 59/80** (2006.01)  
**H04M 1/02** (2006.01)

**H10K 59/12** (2006.01)  
**H10K 59/121** (2006.01)  
**H10K 59/123** (2006.01)  
**H10K 59/65** (2006.01)  
**H10K 71/00** (2006.01)

(52) **U.S. Cl.**  
CPC ..... **H10K 59/873** (2023.02); **H04M 1/0264**  
(2013.01); **H10K 59/1201** (2023.02); **H10K**  
**59/1213** (2023.02); **H10K 59/123** (2023.02);  
**H10K 59/65** (2023.02); **H10K 59/8792**  
(2023.02); **H10K 71/00** (2023.02)

(57) **ABSTRACT**

An electronic device includes a display device and an electronic device. The display device includes a base layer, a circuit element layer, a display element layer, an encapsulation layer, a cover inorganic layer, a cover organic layer, an anti-reflection layer, and a filling part configured to overlap the first area. The electronic device is disposed below the base layer and configured to overlap the first area. A module hole is defined in the display module through which the circuit element layer, the display element layer, the encapsulation layer, the cover inorganic layer, and the cover organic layer overlapping the first area passes through to expose the base layer, and the filling part is disposed inside the module hole and is in contact with a portion of the base layer exposed by the module hole.

